

8.7.03	SHEET U.S. DEPARTMENT OF COMMERCE Patent and Trademark Office
	lease record the attached original documents or copy thereof.
1. Name of conveying party(ies)	2. Name and address of receiving party(ies)
Eisaburo ITAKURA	Name: SONY CORPORATION 7-35 Kitashinagawa 6-chome Shinagawa-Ku, Tokyo 141-0001, Japan
Additional name(s) of conveying party(ies) attached? Yes <u>X</u> No	Additional name(s) & address(es) attached?Yesx No
3. Nature of conveyance:	FICE OF N
X Assignment Security Agreement	CE CE
Merger Change of Name	Sm -5
Other Execution Date(s): July 29, 2003	
4. Application number(s) or patent number(s):	
If this document is being filed together with the application is:	
A. Patent Application No.(s) 10/414,947 filed April	6, 2003
Additional numbers att	ached? Yes <u>X</u> No
Name and address of party to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved 1
Name: WILLIAM S. FROMMER	7. Total fee (37 CFR 3.41)
Internal Address: FROMMER LAWRENCE & HAUG LLP Street Address: 745 FIFTH AVENUE	Authorized to be charged to deposit account 50-0320
City: NEW YORK State: N.Y. Zip: 10151	8. Deposit account number: (Attach duplicate copy of this page if paying by deposit account)
Do not us	e this space
9. Statement and signature.	ormation is true and correct and any attached copy is a true
GORDON KESSLER	August 4, 2003
Name of Person Signing D8/2003 DBYRNE 00000066 10414947	ature Total number of pages including cover sheet, attachments, and document: 2
FC:8021 40.00 OP Do not detac	h this portion
Mail documents to be recorded with	required cover sheet information to:
Director of the US Pat	Recordation Services ent and Trademark Office Box 1450

Public burden reporting for this sample cover sheet is estimated to average about 30 minutes per document to be recorded,

including time for reviewing the document and gathering the data needed, and completing and reviewing the sample cover sheet. Send comments regarding this burden estimate to the U.S. Patent and Trademark Office, Office of Information Systems, PK2-1000C, Washington, D.C. 20231, and to the Office of Management and Budget, Paperwork Reduction Project (0651-0011), Washington, D.C. 20503.

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and

TERMINAL APPARATUS, DATA TRANSMITTING APPARATUS, DATA TRANSMITTING AND RECEIVING SYSTEM, AND DATA TRANSMITTING AND RECEIVING METHOD

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address:

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 7-35 Kitashinagawa 6-Chome, Shinagawa-Ku, Tokyo 141, Japan (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto:

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto:

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: Serial Number: 10/414,947, Filing Date: April 16, 2003.

This assignment executed on the dates indicated below.

Eisaburo ITAKURA		
Name of first or sole inventor	Execution date of U.S. Patent Application	
Kanagawa, Japan		
Residence of first or sole inventor	July 29, 2003	
Signature of first or sole inventor	Date of this assignment	
Name of second inventor	Execution date of U.S. Patent Application	
Residence of second inventor		
Signature of second inventor	Date of this assignment	
Name of third inventor	Execution date of U.S. Patent Application	
Residence of third inventor		
Signature of third inventor	Date of this assignment	

PATENT Page 1 of 1

J:\SONY\04491\FLRCMP.COR (WSF:saa)

REEL: 014354 FRAME: 0764

RECORDED: 08/07/2003